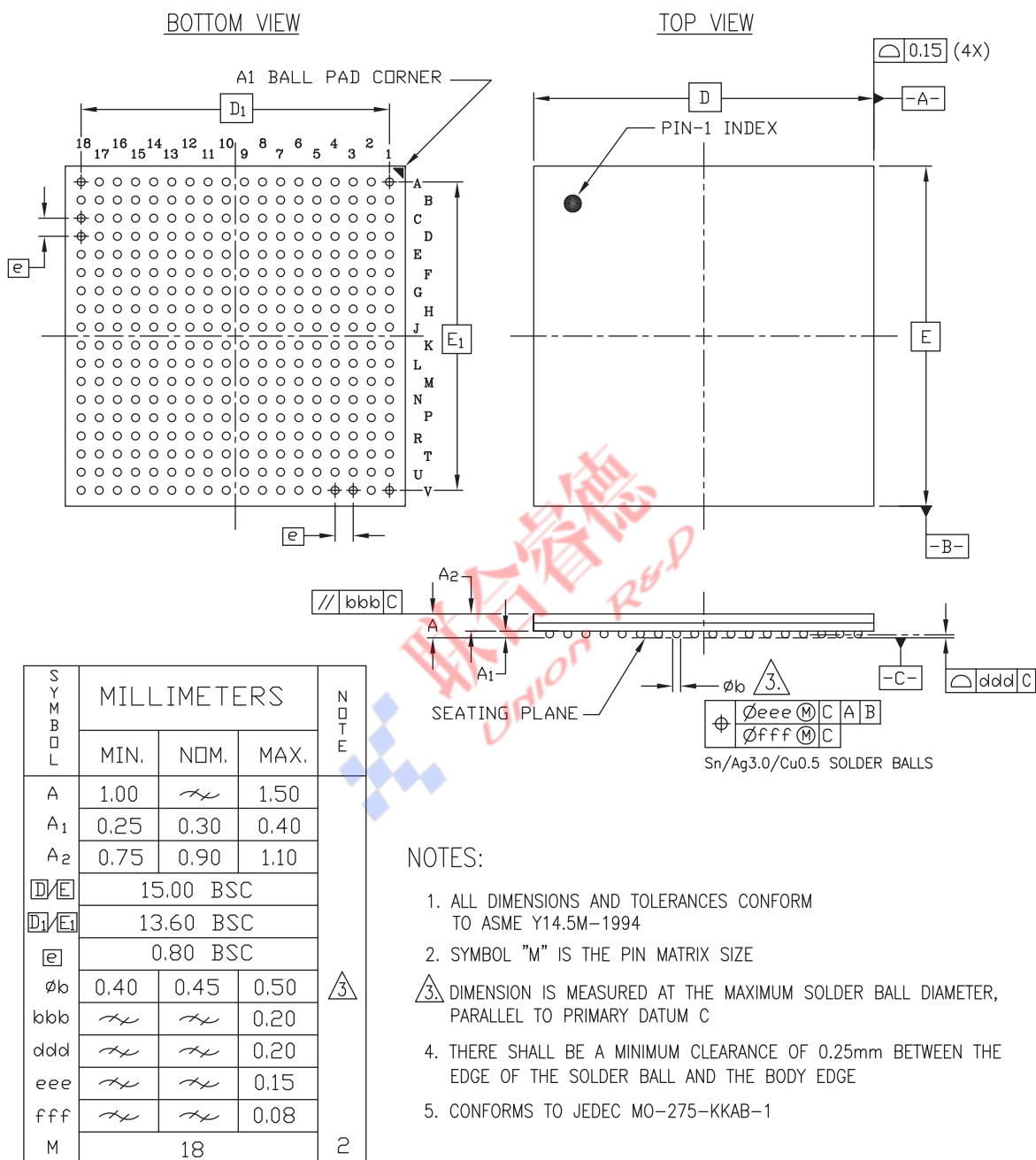


324 Ball Chip-Scale BGA (CSG324) Package, 0.80 mm Pitch



PK381_01_111209

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
06/24/09	1.0	Initial Xilinx release.
11/23/09	1.1	Changed the orientation of the A1 ball pad corner indicator.

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